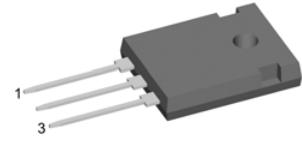
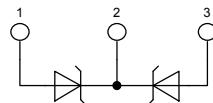


**Schottky Diode Gen 2**

High Performance Schottky Diode  
Low Loss and Soft Recovery  
Common Cathode

**Part number****DSA 70 C 150 HB**

Backside: cathode

**Features / Advantages:**

- Very low V<sub>f</sub>
- Extremely low switching losses
- low I<sub>rm</sub> values
- Improved thermal behaviour
- High reliability circuit operation
- Low voltage peaks for reduced protection circuits
- Low noise switching

**Applications:**

- Rectifiers in switch mode power supplies (SMPS)
- Free wheeling diode in low voltage converters

**Package:**

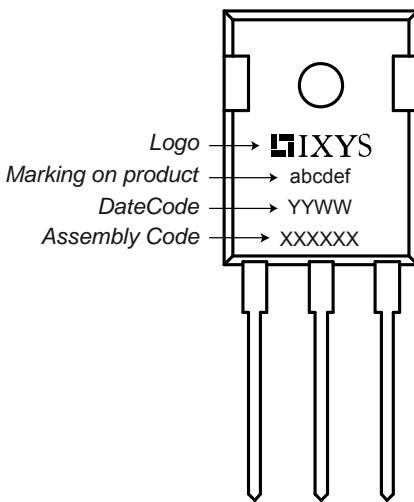
- Housing: TO-247
- Industry standard outline
- Epoxy meets UL 94V-0
- RoHS compliant

Symbol	Definition	Conditions		Ratings		
		min.	typ.	max.	Unit	
V <sub>RRM</sub>	max. repetitive reverse voltage		T <sub>VJ</sub> = 25°C		150	V
I <sub>R</sub>	reverse current	V <sub>R</sub> = 150V	T <sub>VJ</sub> = 25°C		0.68	mA
		V <sub>R</sub> = 150V	T <sub>VJ</sub> = 125°C		7.5	mA
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 35A	T <sub>VJ</sub> = 25°C		0.90	V
		I <sub>F</sub> = 70A			1.06	V
		I <sub>F</sub> = 35A	T <sub>VJ</sub> = 125°C		0.77	V
		I <sub>F</sub> = 70A			0.94	V
I <sub>FAV</sub>	average forward current	rectangular d = 0.5	T <sub>C</sub> = 150°C		35	A
V <sub>F0</sub>	threshold voltage	} for power loss calculation only	T <sub>VJ</sub> = 175°C		0.53	V
r <sub>F</sub>	slope resistance				4.9	mΩ
R <sub>thJC</sub>	thermal resistance junction to case				0.70	K/W
T <sub>VJ</sub>	virtual junction temperature			-55	175	°C
P <sub>tot</sub>	total power dissipation		T <sub>C</sub> = 25°C		215	W
I <sub>FSM</sub>	max. forward surge current	t = 10 ms (50 Hz), sine	T <sub>VJ</sub> = 45°C		420	A
C <sub>J</sub>	junction capacitance	V <sub>R</sub> = 24V; f = 1 MHz	T <sub>VJ</sub> = 25°C	226		pF

Symbol	Definition	Conditions	Ratings		
			min.	typ.	max.
$I_{RMS}$	RMS current	per terminal <sup>1)</sup>			50 A
$R_{thCH}$	thermal resistance case to heatsink			0.25	K/W
$T_{stg}$	storage temperature		-55		150 °C
<b>Weight</b>				6 g	
$M_D$	mounting torque		0.8		1.2 Nm
$F_c$	mounting force with clip		20		120 N

1)  $I_{RMS}$  is typically limited by the pin-to-chip resistance (1); or by the current capability of the chip (2).  
In case of (1) and a common cathode/anode configuration with a non-isolated backside,  
the current capability can be increased by connecting the backside.

### Product Marking

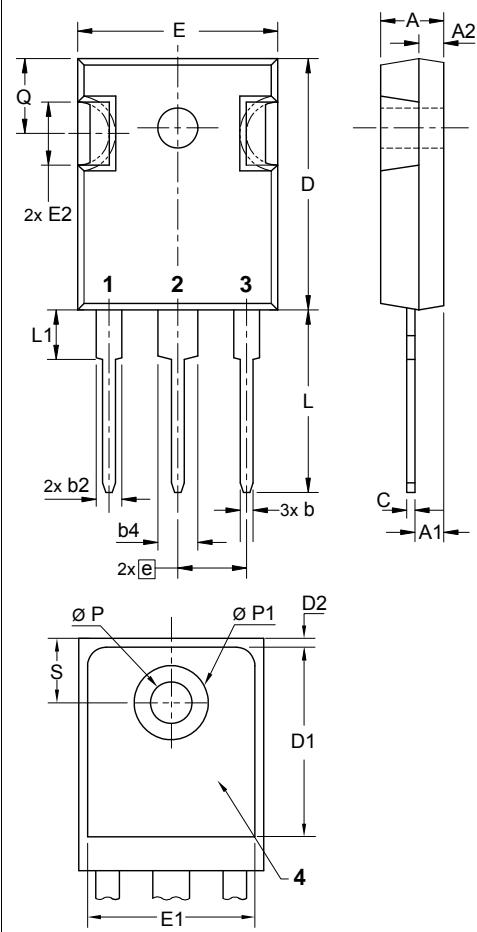


### Part number

D = Diode  
 S = Schottky Diode  
 A = low VF  
 70 = Current Rating [A]  
 C = Common Cathode  
 150 = Reverse Voltage [V]  
 HB = TO-247AD (3)

Ordering	Part Name	Marking on Product	Delivering Mode	Base Qty	Code Key
Standard	DSA 70 C 150 HB	DSA70C150HB	Tube	30	506708

## Outlines TO-247



Sym.	Inches min. max.	Millimeter min. max.
A	0.185 0.209	4.70 5.30
A1	0.087 0.102	2.21 2.59
A2	0.059 0.098	1.50 2.49
D	0.819 0.845	20.79 21.45
E	0.610 0.640	15.48 16.24
E2	0.170 0.216	4.31 5.48
e	0.215 BSC	5.46 BSC
L	0.780 0.800	19.80 20.30
L1	- 0.177	- 4.49
Ø P	0.140 0.144	3.55 3.65
Q	0.212 0.244	5.38 6.19
S	0.242 BSC	6.14 BSC
b	0.039 0.055	0.99 1.40
b2	0.065 0.094	1.65 2.39
b4	0.102 0.135	2.59 3.43
c	0.015 0.035	0.38 0.89
D1	0.515 -	13.07 -
D2	0.020 0.053	0.51 1.35
E1	0.530 -	13.45 -
Ø P1	- 0.29	- 7.39

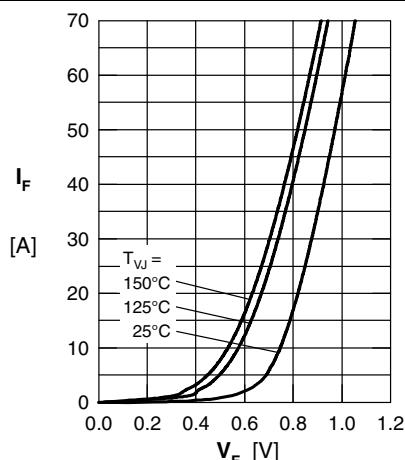


Fig. 1 Maximum forward voltage drop characteristics

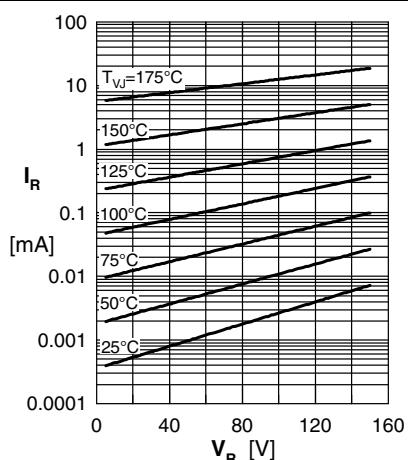


Fig. 2 Typ. reverse current  $I_R$  vs. reverse voltage  $V_R$

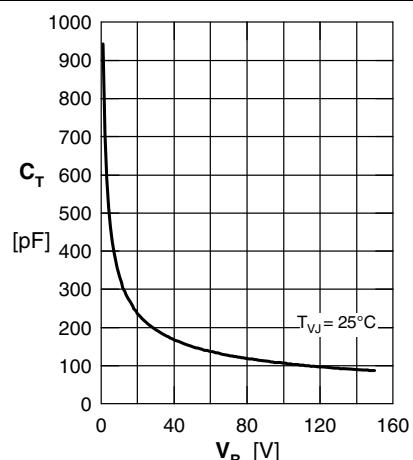


Fig. 3 Typ. junction capacitance  $C_T$  vs. reverse voltage  $V_R$

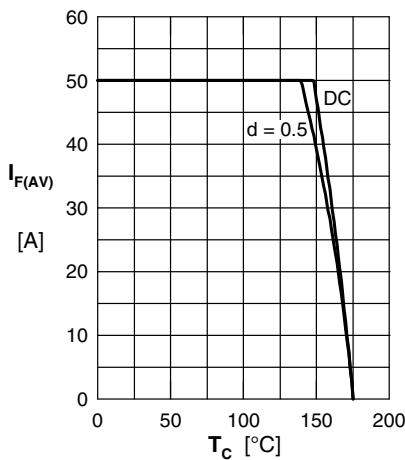


Fig. 4 Average forward current  $I_{F(AV)}$  vs. case temperature  $T_c$

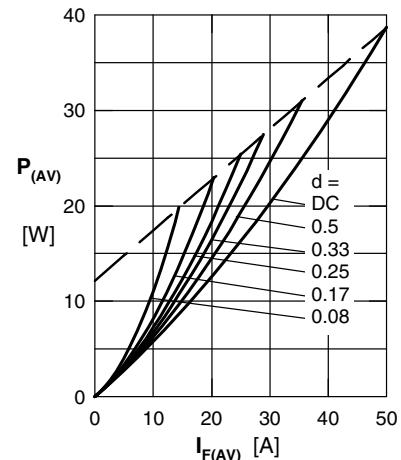


Fig. 5 Forward power loss characteristics

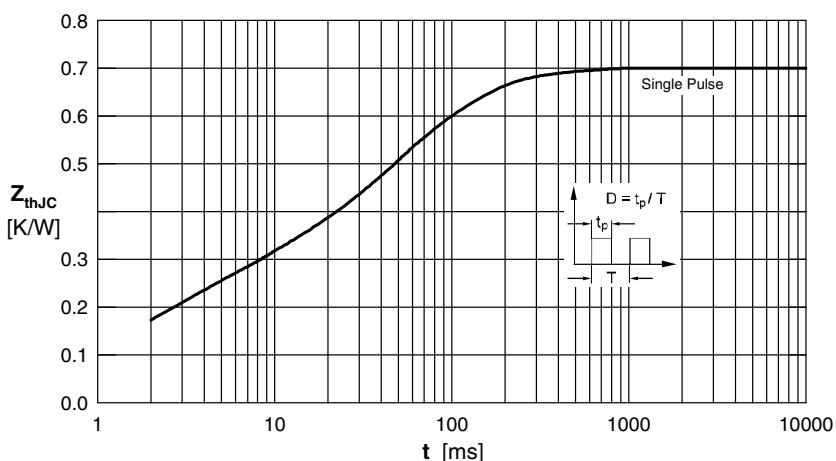


Fig. 6 Transient thermal impedance junction to case

Note: All curves are per diode